

#### **General Description**

The MAX5236/MAX5237 precision, dual, voltage-output, 10-bit digital-to-analog converters (DACs) consume only 360µA from a single 5V (MAX5237) or 325µA from a single 3V (MAX5236) supply. These devices feature output buffers that swing Rail-to-Rail®. The internal gain amplifiers (1.6384V/V) maximize the dynamic range of the DAC output.

The MAX5236/MAX5237 feature 13.5MHz a 3-wire serial interface compatible with SPI™/QSPI™/and MICROWIRE™. Each DAC input is organized as an input register followed by a DAC register. A 16-bit shift register loads data into the input registers. Input registers update the DAC registers independently or simultaneously. In addition, programmable control bits allow power-down with  $1k\Omega$  or  $200k\Omega$  internal loads.

The MAX5236/MAX5237 are fully specified over the extended industrial temperature range (-40°C to +85°C) and are available in space-saving 10-pin µMAX packages.

### **Applications**

Industrial Process Controls Automatic Test Equipment Digital Offset and Gain Adjustment Motion Control μP-Controlled Systems

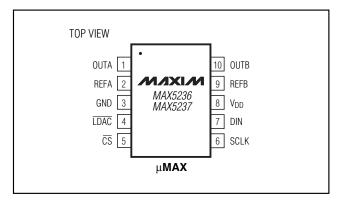
#### Features

- ♦ Guaranteed 1/2LSB INL (max)
- **♦ Low Supply Current** 325µA (Normal Operation) 0.4µA (Full Power-Down Mode)
- **♦** Single-Supply Operation 3V (MAX5236) 5V (MAX5237)
- ♦ Space-Saving 10-Pin µMAX Package
- ♦ Output Buffers Swing Rail-to-Rail
- ♦ Power-On Reset Clears Registers and DACs to Zero
- ♦ Programmable Shutdown Modes with 1kΩ or 200kΩ Internal Loads
- ♦ Resets to Zero
- **♦ 13.5MHz SPI/QSPI/MICROWIRE-Compatible**, 3-Wire Serial Interface
- ♦ Buffered Output Drives 5kΩ || 100pF

### **Ordering Information**

PART	TEMP RANGE	PIN- PACKAGE	INL (LSB)	
MAX5236EUB	-40°C to +85°C	10 μMAX	±0.5	
MAX5237EUB	-40°C to +85°C	10 μMAX	±0.5	

### Pin Configuration



Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd. SPI/QSPI are trademarks of Motorola, Inc.

MICROWIRE is a trademark of National Semiconductor Corp.

#### **ABSOLUTE MAXIMUM RATINGS**

$\begin{array}{llllllllllllllllllllllllllllllllllll$	Storage Temperature Range65°C to +150°C Lead Temperature Range (soldering, 10s )+300°C
10-Pin uMAX (derate 5.60mW/°C above +70°C)444mV	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS—MAX5237**

 $(V_{DD} = +4.5V \text{ to } +5.5V, \text{ GND} = 0, V_{REFA} = V_{REFB} = +2.5V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$ 

PARAMETER SYM		BOL CONDITIONS		TYP	MAX	UNITS
STATIC PERFORMANCE	· I	,	I.			
Resolution	N		10			Bits
Integral Nonlinearity	INL	(Note 1)			±0.5	LSB
Differential Nonlinearity	DNL				±1	LSB
Offset Error	Vos	(Note 2)			±5	mV
Gain Error					±3	LSB
Full-Scale Voltage	VFS	Code = 3FFhex, T <sub>A</sub> = +25°C (Note 3)	4.084	4.092	±4.100	V
Full-Scale Temperature Coefficient	ature TCV <sub>FS</sub> Normalized to 4.095V			2		ppm/°C
Offset Temperature Coefficient	TCVos			±8		μV/°C
Power-Supply Rejection	PSR	4.5V ≤ V <sub>DD</sub> ≤ 5.5V		15	200	μV
DC Crosstalk		(Note 4)			100	μV
REFERENCE INPUT						
Reference Input Range	V <sub>REF</sub>	(Note 5)	0.25		2.60	V
Reference Input Resistance	R <sub>REF</sub>	Minimum with code 155 hex and 2AA hex	28	37		kΩ
Reference Current in Shutdown	IREF				±1	μΑ
MULTIPLYING MODE PERFORM	IANCE					
Reference -3dB Bandwidth, Input code = 3FF hex, V <sub>REF</sub> = 0.5V <sub>P-P</sub> + 1.5V <sub>DC</sub>			350		kHz	
Reference Feedthrough		Input code = 000 hex, V <sub>REF</sub> _ = 3.6V <sub>P-P</sub> + 1.8V <sub>DC</sub> , f = 1kHz		_	dB	
Signal-to-Noise plus Distortion Ratio	SINAD	Input code = 3FF hex, V <sub>REF</sub> _ = 2V <sub>P-P</sub> + 1.5V <sub>DC</sub> , f = 10kHz	79		dB	

### **ELECTRICAL CHARACTERISTICS—MAX5237 (continued)**

 $(V_{DD} = +4.5V \text{ to } +5.5V, \text{ GND} = 0, V_{REFA} = V_{REFB} = +2.5V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIGITAL INPUT			•			•
Input High Voltage	VIH		0.7 × V <sub>DD</sub>			V
Input Low Voltage	VIL				0.3 × V <sub>DD</sub>	V
Input Hysteresis	V <sub>HYS</sub>			200		mV
Input Leakage Current		Digital inputs = 0 or V <sub>DD</sub>			±1	μΑ
Input Capacitance				8		рF
DYNAMIC PERFORMANCE						
Voltage-Output Slew Rate	SR			0.6		V/µs
Voltage-Output Settling Time		To $\pm 0.5$ LSB, $V_{STEP} = \pm 4V$ , $0.25V \le V_{OUT} \le (V_{DD} - 0.25V)$		10		μs
Output-Voltage Swing		(Note 6)		0 to V <sub>DD</sub>		V
Time Required for Output to Settle After Turning on V <sub>DD</sub>		(Note 7)			70	μs
Time Required for Output to Settle After Exiting Full Power- Down		(Note 7)			70	μs
Time Required for Output to Settle After Exiting DAC Power- Down		(Note 7)			60	μs
Digital Feedthrough		$\overline{\text{CS}} = \text{V}_{\text{DD}},  \text{f}_{\text{SCLK}} = 100 \text{kHz},  \text{V}_{\text{SCLK}} = 5 \text{V}_{\text{P-P}}$		5		nV-s
Major Carry Glitch Energy				40		nV-s
POWER SUPPLIES						
Power-Supply Voltage	$V_{DD}$		4.5		5.5	V
Power-Supply Current			450	μA		
		Full power-down mode		1	5	
Power-Supply Current in Power- Down and Shutdown Modes	I <sub>SHDN</sub>	One DAC shutdown mode		190	215	μΑ
Down and Shridown Modes		Both DACs shutdown mode		26	42	

#### **ELECTRICAL CHARACTERISTICS—MAX5236**

 $(V_{DD} = +2.7 V \text{ to } +3.6 V, \text{ GND} = 0, V_{REFA} = V_{REFB} = +1.25 V, R_L = 5 k\Omega, C_L = 100 pF, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $T_A = +25 ^{\circ}\text{C.})$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
STATIC PERFORMANCE						
Resolution	N		10			Bits
Integral Nonlinearity	INL	(Note 1)			±0.5	LSB
Differential Nonlinearity	DNL				±1	LSB
Offset Error	Vos	(Note 2)			±5	mV
Gain Error	GE				±6	LSB
Full-Scale Voltage	V <sub>FS</sub>	Code = FFFhex, T <sub>A</sub> = +25°C (Note 3)	2.039	2.046	2.053	V
Full-Scale Temperature Coefficient	TCVFS	Normalized to 2.0475V		4		ppm/°C
Offset Temperature Coefficient	TCV <sub>OS</sub>			±8		μV/°C
Power-Supply Rejection	PSR	$2.7V \le V_{DD} \le 3.6V$		18	280	μV
DC Crosstalk		(Note 4)			100	μV
REFERENCE INPUT						
Reference Input Range	V <sub>REF</sub>	(Note 5)	0.25		1.50	V
Reference Input Resistance	R <sub>REF</sub>	Minimum with code 155 hex and 2AA hex	28	37		kΩ
Reference Current in Shutdown	I <sub>REF</sub>				±1	μΑ
MULTIPLYING MODE PERFORM	ANCE					
Reference -3dB Bandwidth, Slew-Rate Limited		Input code = 3FF hex, V <sub>REF</sub> _ = 0.5V <sub>P-P</sub> + 0.75V <sub>DC</sub>		350		kHz
Reference Feedthrough		Input code = 000 hex, V <sub>REF</sub> _ = 1.6V <sub>P-P</sub> + 0.8V <sub>DC</sub> , f = 1kHz		-80		dB
Signal-to-Noise plus Distortion Ratio	SINAD	Input code = 3FF hex, V <sub>REF</sub> _ = 0.6V <sub>P-P</sub> + 0.9V <sub>DC</sub> , f = 10kHz		79		dB
DIGITAL INPUTS						1
Input High Voltage	V <sub>IH</sub>		0.7 × V <sub>DD</sub>			V
Input Low Voltage	VIL				0.3 × V <sub>DD</sub>	V
Input Hysteresis	V <sub>HYS</sub>			200		mV
Input Leakage Current		Digital inputs = 0 or V <sub>DD</sub>			±1	μΑ
Input Capacitance				8		рF
DYNAMIC PERFORMANCE						
Voltage-Output Slew Rate	SR			0.6		V/µs
Voltage-Output Settling Time		To ±0.5LSB, $V_{STEP} = \pm 2V$ , $0.25V \le V_{OUT} \le (V_{DD} - 0.25V)$		10		μs
Output-Voltage Swing		(Note 6) 0 to V <sub>DD</sub>			V	

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#### **ELECTRICAL CHARACTERISTICS—MAX5236 (continued)**

 $(V_{DD} = +2.7V \text{ to } +3.6V, \text{ GND} = 0, V_{REFA} = V_{REFB} = +1.25V, R_L = 5k\Omega, C_L = 100pF, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS		TYP	MAX	UNITS
Time Required for Output to Settle After Turning on V <sub>DD</sub>		(Note 7)			60	μs
Time Required for Output to Settle After Exiting Full Power- Down		(Note 7)			60	μs
Time Required for Output to Settle After Exiting DAC Power- Down		(Note 7)			50	μs
Digital Feedthrough		$\overline{\text{CS}} = \text{V}_{\text{DD}},  \text{f}_{\text{SCLK}} = 100 \text{kHz},  \text{V}_{\text{SCLK}} = 3 \text{V}_{\text{P-P}}$		5		nV-s
Major Carry Glitch Energy				115		nV-s
POWER SUPPLIES						
Power-Supply Voltage	$V_{DD}$		2.7		3.6	V
Power-Supply Current	I <sub>DD</sub>	(Note 8)		325	430	μΑ
		Full power-down mode		0.4	5	
Power-Supply Current in Power- Down and Shutdown Modes	ISHDN	One DAC shutdown mode		175	200	μΑ
Down and Ghalaown Woods		Both DACs shutdown mode		25	40	

### TIMING CHARACTERISTICS—MAX5237 (FIGURES 1 AND 2)

 $(V_{DD} = +4.5V \text{ to } +5.5V, \text{ GND} = 0, \text{ T}_{A} = \text{T}_{MIN} \text{ to T}_{MAX}, \text{ unless otherwise noted. Typical values are at T}_{A} = +25^{\circ}\text{C.})$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCLK Clock Period	tcp		74			ns
SCLK Pulse Width High	tcH		30			ns
SCLK Pulse Width Low	t <sub>CL</sub>		30			ns
CS Fall to SCLK Rise Setup Time	tcss		30			ns
SCLK Rise to CS Rise Hold Time	tcsh		0			ns
DIN Setup Time	t <sub>DS</sub>		30			ns
DIN Hold Time	t <sub>DH</sub>		0			ns
SCLK Rise to CS Fall Delay	t <sub>CS0</sub>		10			ns
CS Rise to SCLK Rise Hold Time	tcs1		30			ns
CS Pulse Width High	tcsw		75			ns
LDAC Pulse Width Low	t <sub>LDL</sub>		30			ns
CS Rise to LDAC Rise Hold Time	tcsld	(Note 9)	40			ns

### TIMING CHARACTERISTICS—MAX5236 (FIGURES 1 AND 2)

 $(V_{DD} = +2.7V \text{ to } +3.6V, \text{ GND} = 0, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCLK Clock Period	tCP		74			ns
SCLK Pulse Width High	tcH		30			ns
SCLK Pulse Width Low	tCL		30			ns
CS Fall to SCLK Rise Setup Time	tcss		30			ns
SCLK Rise to $\overline{\text{CS}}$ Rise Hold Time	tcsh		0			ns
DIN Setup Time	t <sub>DS</sub>		30			ns
DIN Hold Time	tDH		0			ns
SCLK Rise to CS Fall Delay	tcso		10			ns
CS Rise to SCLK Rise Hold Time	t <sub>CS1</sub>		30			ns
CS Pulse Width High	tcsw		75			ns
LDAC Pulse Width Low	t <sub>LDL</sub>		30			ns
CS Rise to LDAC Rise Hold Time	tcsld	(Note 9)	75			ns

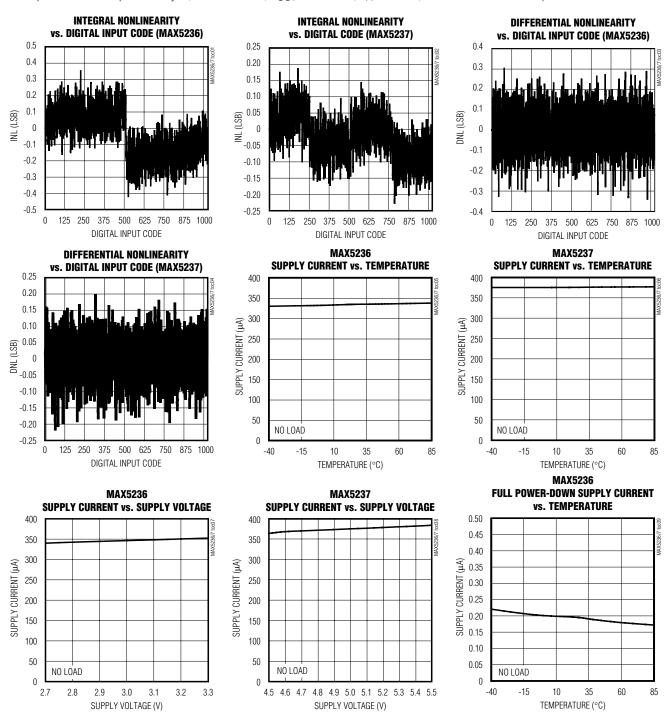
Note 1: Accuracy is guaranteed in the following way:

$V_{DD}$	V <sub>REF</sub> _	ACCURACY GUARANTEED FROM CODE	TO CODE
3	1.250	6	1023
5	2.500	3	1023

- Note 2: Offset is measured at the code closest to 12mV.
- **Note 3:** Gain from V<sub>REF</sub> to V<sub>OUT</sub> is typically 1.638 × CODE/1024.
- Note 4: DC crosstalk is measured as follows: set DAC A to midscale, and DAC B to zero, and measure DAC A output; then change DAC B to full scale and measure ΔV<sub>OUT</sub> for DAC A. Repeat the same measurement with DAC A and DAC B interchanged. DC crosstalk is the maximum ΔV<sub>OUT</sub> measured.
- Note 5: The DAC output voltage is derived by gaining up V<sub>REF</sub> by 1.638 × CODE/1024. This gain factor may cause V<sub>OUT</sub> to try to exceed the supplies. The maximum value of V<sub>REF</sub> in the reference input range spec prevents this from happening at full scale. The minimum V<sub>REF</sub> value of 0.25V is determined by linearity constraints, not DAC functionality.
- **Note 6:** Accuracy is better than 1LSB for  $V_{OUT} = 12mV$  to  $V_{DD}$  180mV.
- Note 7: Guaranteed by design. Not production tested.
- Note 8:  $R_{LOAD} = \infty$  and digital inputs are at either  $V_{DD}$  or GND.  $V_{OUT} = \text{full-scale}$  output voltage.
- Note 9: This timing requirement applies only to CS rising edges, which execute commands modifying the DAC input register contents.

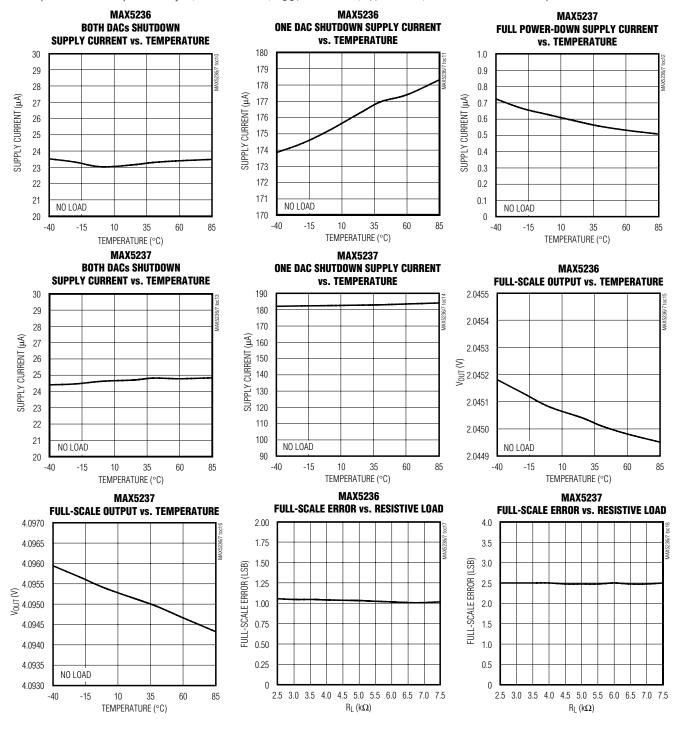
### **Typical Operating Characteristics**

 $(V_{DD} = +5V \text{ (MAX5237)} V_{DD} = +3V \text{ (MAX5236)}, R_L = 5k\Omega, C_L = 100pF, V_{REF} = +1.25V \text{ (MAX5236)}, V_{REF} = +2.5V \text{ (MAX5237)}, C_{REF} = 0.1 \mu F \text{ ceramic II } 2.2 \mu F \text{ electrolytic, both DACs on, } V_{OUT} = \text{ full scale, } T_A = +25^{\circ}\text{C, unless otherwise noted.})$ 



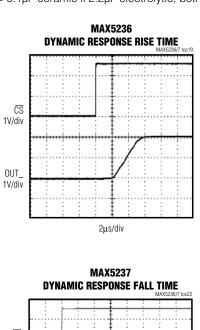
### Typical Operating Characteristics (continued

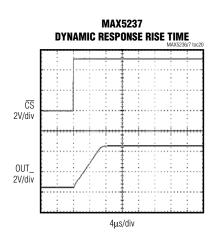
 $(V_{DD} = +5V \text{ (MAX5237)} \ V_{DD} = +3V \text{ (MAX5236)}, \ R_L = 5k\Omega, \ C_L = 100 \text{pF}, \ V_{REF} = +1.25V \text{ (MAX5236)}, \ V_{REF} = +2.5V \text{ (MAX5237)}, \ C_{REF} = 0.1 \mu \text{F} \ \text{ceramic II } 2.2 \mu \text{F} \ \text{electrolytic, both DACs on, } V_{OUT} = \text{full scale, } T_A = +25^{\circ}\text{C, unless otherwise noted.})$ 

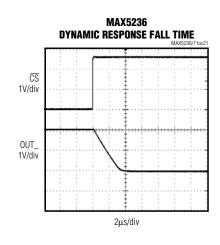


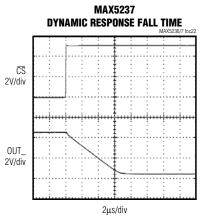
### Typical Operating Characteristics (continued)

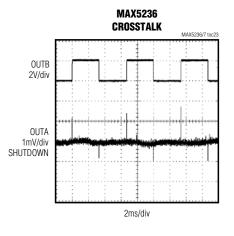
 $(V_{DD} = +5V \text{ (MAX5237) } V_{DD} = +3V \text{ (MAX5236)}, \ R_L = 5k\Omega, \ C_L = 100 pF, \ V_{REF} = +1.25V \text{ (MAX5236)}, \ V_{REF} = +2.5V \text{ (MAX5237)}, \ C_{REF} = 0.1 \mu F \text{ ceramic II } 2.2 \mu F \text{ electrolytic, both DACs on, } V_{OUT} = \text{full scale, } T_A = +25^{\circ}\text{C, unless otherwise noted.})$ 

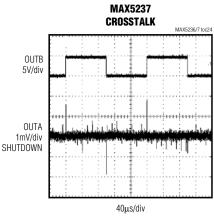


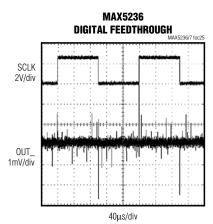


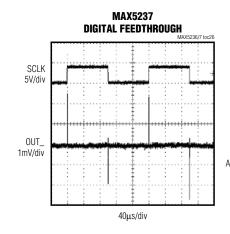


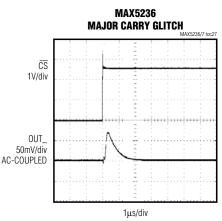






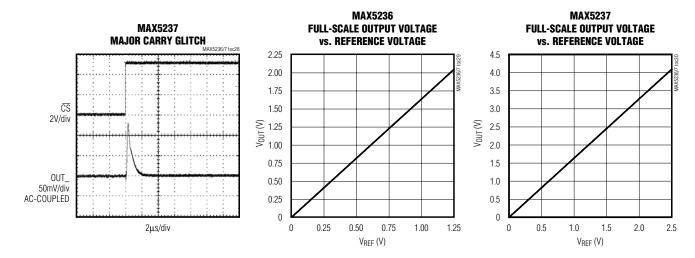






### Typical Operating Characteristics (continued)

 $(V_{DD} = +5V \text{ (MAX5237)} V_{DD} = +3V \text{ (MAX5236)}, R_L = 5k\Omega, C_L = 100pF, V_{REF} = +1.25V \text{ (MAX5236)}, V_{REF} = +2.5V \text{ (MAX5237)}, C_{REF} = 0.1 \mu F$  ceramic II 2.2  $\mu$ F electrolytic, both DACs on,  $V_{OUT} = \text{full scale}, T_A = +25^{\circ}\text{C}$ , unless otherwise noted.)



### **Pin Description**

PIN	NAME	FUNCTION
1	OUTA	DAC A Output
2	REFA	Reference for DAC A
3	GND	Ground
4	LDAC	Load DACs A and B
5	<u>CS</u>	Chip Select Input
6	SCLK	Shift Register Serial Clock Input
7	DIN	Serial Data Input
8	$V_{DD}$	Positive Supply
9	REFB	Reference for DAC B
10	OUTB	DAC B Output

#### **Detailed Description**

The MAX5236/MAX5237 10-bit, voltage-output DACs are easily configured with a 3-wire SPI/QSPI/MICROWIRE serial interface. The devices include a 16-bit data-in/data-out shift register and have an input consisting of an input register and a DAC register. In addition, these devices employ precision trimmed internal resistors to produce a gain of 1.6384V/V, maximizing the output voltage swing, and a programmable shutdown output impedance of  $1 k\Omega$  or  $200 k\Omega$ . The full-scale output voltage is 4.092V for the MAX5237 and 2.046V for the MAX5236. These devices produce a

weighted output voltage proportional to the digital input code with an inverted rail-to-rail ladder network (Figure 3).

#### **External Reference**

The reference inputs accept both AC and DC values with a voltage range extending from 0.25V to 2.6V for the MAX5237 and 0.25V to 1.5V for the MAX5236. For proper operation **do not** exceed the input voltage range limits. Determine the output voltage using the following equation:

$$V_{OUT} = (V_{REF} \times NB / 1024) \times 1.6384V/V$$

where NB is the numeric value of the DACs binary input code (0 to 1023), V<sub>REF</sub> is the reference voltage, and 1.6384V/V is the gain of the internal output amplifier.

The code-dependent reference input impedance ranges from a minimum of  $28k\Omega$  to several  $G\Omega$  at code 0. The code-dependent reference input capacitance is typically 23pF.

#### Output Amplifier

The output amplifiers have internal resistors that provide for a gain of 1.6384V/V. These trimmed resistors minimize gain error. The output amplifiers have a typical slew rate of 0.6V/ $\mu$ s and settle to 1/2LSB within 10 $\mu$ s (typ) with a load of 5k $\Omega$  in parallel with 100pF. Use the serial interface to set the shutdown output impedance of the amplifiers to 1k $\Omega$  or 200k $\Omega$ .

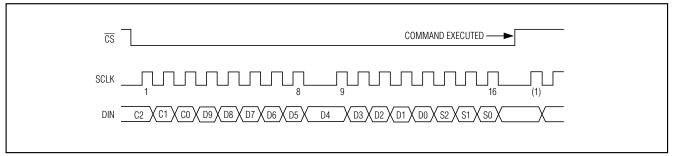


Figure 1. Serial Interface Timing

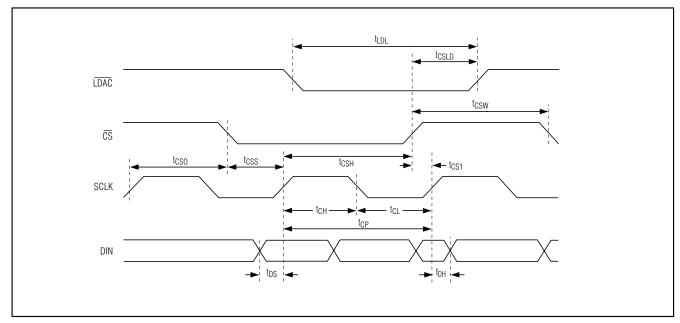


Figure 2. Detailed Serial Interface Timing

#### Serial Interface

The 3-wire serial interface (SPI/ QSPI/ and MICROWIRE compatible) used in the MAX5236/MAX5237 allows for complete control of DAC operations (Figures 4 and 5). Figures 1 and 2 show the timing for the serial interface. The serial word consists of 3 control bits followed by 10 data bits (MSB first) and 3 sub-bits as described in Tables 1, 2, and 3. When the 3 control bits are all zero or all 1, D9–D6 are used as additional control bits, allowing for greater DAC functionality.

The digital inputs allow any of the following: loading the input register(s) without updating the DAC register(s), updating the DAC register(s) from the input register(s), or updating the input and DAC register(s) simultane-

ously. The control bits and D9-D6 allow the DACs to operate independently.

Send the 16-bit data as one 16-bit word (QSPI) or two 8-bit packets (SPI and MICROWIRE), with  $\overline{CS}$  low during this period. The control bits and D9-D6 determine which registers update and the state of the registers when exiting shutdown. The 3-bit control and D9-D6 determine the following:

- · Registers to be updated
- Selection of the power-down modes

#### **Table 1. Serial Data Format**

MSB <> LSB					
3 Control Bits	ontrol Bits MSB10 Data BitsLSB Sub-Bits				
C2C0	D9D0	S2S0			

The general timing diagram of Figure 1 illustrates data acquisition. Driving  $\overline{CS}$  low enables the device to receive data. Otherwise the interface control circuitry is disabled. With  $\overline{CS}$  low, data at DIN is clocked into the register on the rising edge of SCLK. As  $\overline{CS}$  goes high, data is latched into the input and/or DAC registers, depending on the control bits and D9–D6. The maximum clock frequency guaranteed for proper operation is 13.5MHz. Figure 2 depicts a more detailed timing diagram of the serial interface.

#### **Power-Down and Shutdown Modes**

As described in Tables 2 and 3, several serial interface commands put one or both of the DACs into shutdown mode. Shutdown modes are completely independent for each DAC. In shutdown, the amplifier output becomes high impedance, and OUT\_ terminates to GND through the 200k $\Omega$  (typ) gain resistors. Optionally (see Tables 2 and 3), OUT\_ can have an additional termination of 1k $\Omega$  to GND.

Full power-down mode shuts down the main bias generator and both DACs. The shutdown impedance of the DAC outputs can still be controlled independently, as described in Tables 2 and 3.

A serial interface command exits shutdown mode and updates a DAC register. Each DAC can exit shutdown at the same time or independently (see Tables 2 and 3). For example, if both DACs are shut down, updating the DAC A register causes DAC A to power up, while DAC B remains shutdown. In full power-down mode, powering up either DAC also powers up the main bias generator. To change from full power-down to both DACs shutdown mode requires the waking of at least one DAC between states.

When powering up the MAX5236/MAX5237 (powering VDD) allow 60 $\mu$ s (MAX5236) or 70 $\mu$ s (MAX5237) for the output to stabilize. When exiting full power-down mode, allow 60 $\mu$ s max (MAX5236) or 70 $\mu$ s max (MAX5237) for the output to stabilize. When exiting DAC shutdown mode allow 50 $\mu$ s max (MAX5236) or 60 $\mu$ s max (MAX5237) for the output to stabilize.

#### Load DAC Input (LDAC)

Asserting LDAC asynchronously loads the DAC registers from their corresponding input registers (DACs that are shut down remain shut down). The LDAC input is

totally asynchronous and does not require any activity on  $\overline{CS}$ , SCLK, or DIN in order to take effect. If  $\overline{LDAC}$  is asserted coincident with a rising edge of  $\overline{CS}$ , which executes a serial command modifying the value of either DAC input register, then  $\overline{LDAC}$  must remain asserted for at least 30ns following the  $\overline{CS}$  rising edge. This requirement applies only for serial commands that modify the value of the DAC input registers.

### **Applications Information**

#### **Definitions**

#### Integral Nonlinearity (INL)

Integral nonlinearity (Figure 6a) is the deviation of the values on an actual transfer function from a straight line. This straight line can be either a best-straight-line fit (closest approximation to the actual transfer curve) or a line drawn between the endpoints of the transfer function, once offset and gain errors have been nullified. For a DAC, the deviations are measured at every single step.

#### Differential Nonlinearity (DNL)

Differential nonlinearity (Figure 6b) is the difference between an actual step height and the ideal value of 1LSB. If the magnitude of the DNL is less than 1LSB, the DAC guarantees no missing codes and is monotonic.

#### Offset Error

The offset error (Figure 6c) is the difference between the ideal and the actual offset point. For a DAC, the offset point is the step value when the digital input is zero. This error affects all codes by the same amount and can usually be compensated for by trimming.

#### Gain Erroi

Gain error (Figure 6d) is the difference between the ideal and the actual full-scale output voltage on the transfer curve, after nullifying the offset error. This error alters the slope of the transfer function and corresponds to the same percentage error in each step.

#### Settling Time

The settling time is the amount of time required from the start of a transition until the DAC output settles to its new output value within the converter's specified accuracy.

#### Digital Feedthrough

Digital feedthrough is noise generated on the DAC's output when any digital input transitions. Proper board layout and grounding significantly reduce this noise, but there is always some feedthrough caused by the DAC itself.

**Table 2. Serial Interface Programming Commands** 

		16	-BIT SERIAL WORD		
C2	C1	CO	D9D0	S2, S1, S0*	FUNCTION
0	0	1	10-bit DAC data	000	Load input register A; DAC registers are unchanged.
0	1	0	10-bit DAC data	000	Load input register A; all DAC registers are updated.
0	1	1	10-bit DAC data	000	Load all DAC registers from the shift register (start up both DACs with new data, and load the input registers).
1	0	0	xxxxxxxx	000	Update both DAC registers from their respective input registers (start up both DACs with data previously stored in the input registers).
1	0	1	10-bit DAC data	000	Load input register B; DAC registers are unchanged.
1	1	0	10-bit DAC data	000	Load input register B; all DAC registers are updated.
1	1	1	P1A P1B X X X X X X X X	000	Power down both DACs respectively according to bits P1A and P1B (see Table 3). Internal bias remains active.
0	0	0	001XXXXXX	000	Update DAC register A from input register A (start up DAC A with data previously stored in input register A).
0	0	0	0 1 1 P1A P1B X X X X X	000	Full power-down. Power down the main bias generator and power down both DACs respectively according to bits P1A and P1B (see Table 3).
0	0	0	1 0 1 X X X X X X	000	Update DAC register B from input register B (start up DAC B with data previously stored in input register B).
0	0	0	1 1 0 P1A X X X X X X	000	Power down DAC A according to bit P1A (see Table 3).
0	0	0	1 1 1 P1B X X X X X X	000	Power down DAC B according to bit P1B (see Table 3).

X = Don't care.

#### **Unipolar Output**

Figure 7 shows the MAX5236/MAX5237 configured for unipolar, rail-to-rail operation with a gain of 1.6384V/V. The MAX5237 produces a 0 to 4.092V output with 2.5V reference, while the MAX5236 produces a range of 0 to 2.046V output with a 1.25V reference. Table 4 lists the unipolar output codes.

#### **Bipolar Output**

The MAX5236/MAX5237 can be configured for a bipolar output, as shown in Figure 8. The output voltage is given by the equation:

 $V_{OUT} = V_{REF} [((1.6348 \times NB) / 1024) - 1]$ 

where NB represents the numeric value of the DAC's binary input code. Table 5 shows digital codes and the corresponding output voltage for Figure 8's circuit.

#### Using an AC Reference

In applications where the reference has an AC signal component, the MAX5236/MAX5237 have multiplying

#### **Table 3. P1 Shutdown Modes**

P1(A/B)	SHUTDOWN MODE	
0	Shut down with internal 1k $\Omega$ load to GND	
1	Shut down with internal 200k $\Omega$ load to GND	

capabilities within the reference input voltage range specifications. Figure 9 shows a technique for applying a sinusoidal input to REF\_, where the AC signal is offset before being applied to the reference input.

## Digital Calibration and Threshold Selection

Figure 10 shows the MAX5236/MAX5237 in a digital calibration application. With a bright light value applied to the photodiode (on), the DAC is digitally ramped until it trips the comparator. The microprocessor ( $\mu$ P) stores this "high" calibration value. Repeat the process with a dim light (off) to obtain the dark current calibration. The  $\mu$ P then programs the DAC to set an output voltage at

<sup>\* =</sup> S2, S1, and S0 must be zero for proper operation.

Table 4. Unipolar Code Table (Gain = 1.6384)

DAC CONTENTS	ANALOG OUTPUT
MSB LSB	
1111 1111 1 1 (000)	$+V_{REF} \left(\frac{1023}{1024}\right) \times 1.6384$
1000 0000 0 1 (000)	$+V_{REF} \left( \frac{513}{1024} \right) \times 1.6384$
1000 0000 0 0 (000)	$+V_{REF} \left( \frac{512}{1024} \right) \times 1.6384 = V_{REF}$
0111 1111 1 1 (000)	$+V_{REF} \left( \frac{511}{1024} \right) \times 1.6384$
0000 0000 01 (000)	$+V_{REF}\left(\frac{1}{1024}\right) \times 1.6384$
0000 0000 0 0 (000)	OV

Note: () are for the sub-bit.

**Table 5. Bipolar Code Table** 

DAC CONTENTS	ANALOG CUTPUT
MSB LSB	ANALOG OUTPUT
1111 1111 1 1 (000)	$+V_{REF}\left(\frac{511}{512}\right)$
1000 0000 0 1 (000)	$+V_{REF}\left(\frac{1}{512}\right)$
1000 0000 0 0 (000)	OV
0111 1111 11 (000)	$-V_{REF}\left(\frac{1}{512}\right)$
0000 0000 01 (000)	$-V_{REF}\left(\frac{511}{512}\right)$
0000 0000 00 (000)	$-V_{REF}\left(\frac{512}{512}\right) = -V_{REF}$

Note: () are for the sub-bit.

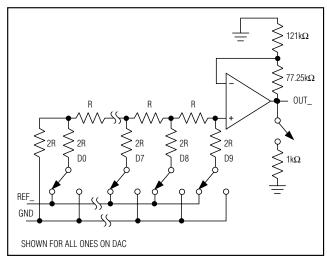


Figure 3. Simplified DAC Circuit Diagram

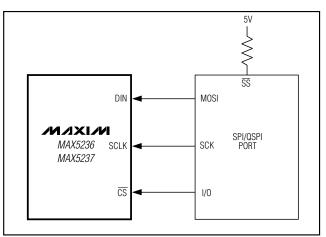


Figure 4. SPI/QSPI Interface Connections

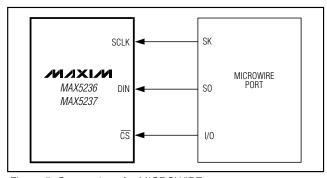


Figure 5. Connections for MICROWIRE

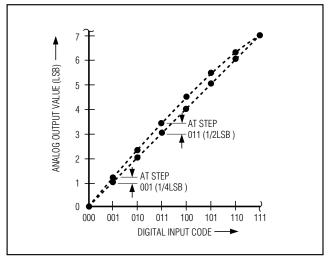


Figure 6a. Integral Nonlinearity

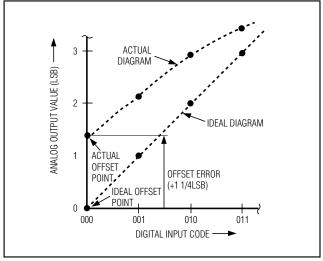


Figure 6c. Offset Error

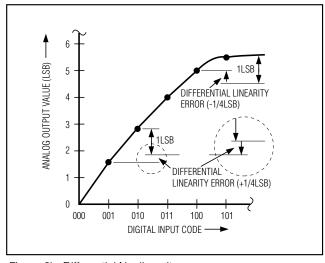


Figure 6b. Differential Nonlinearity

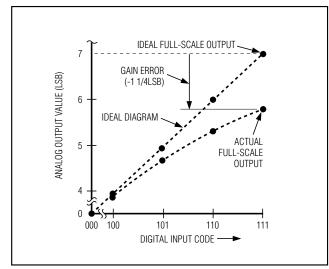


Figure 6d. Gain Error

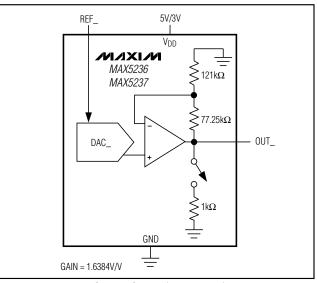


Figure 7. Unipolar Output Circuit (Rail-to-Rail)

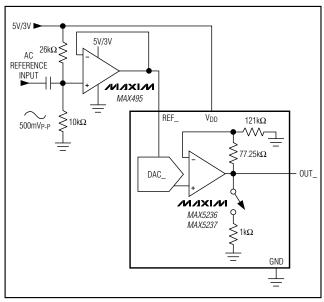


Figure 9. External Reference with AC Components

the midpoint of the two calibrated values. Applications include tachometers, motion sensing, automatic readers, and liquid clarity analysis.

#### **Digital Control of Gain and Offset**

The two DACs can be used to control the offset and gain for curve-fitting nonlinear functions, such as transducer linearization or analog compression/expansion applications. The input signal is used as the reference

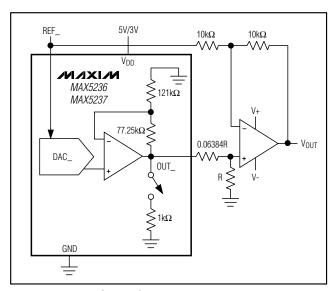


Figure 8. Bipolar Output Circuit

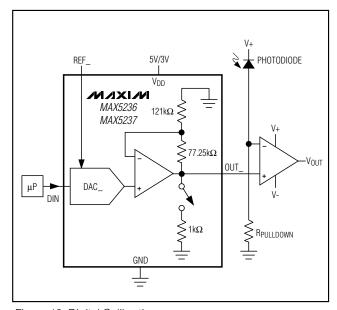


Figure 10. Digital Calibration

for the gain-adjust DAC, whose output is summed with the output from the offset-adjust DAC. The relative weight of each DAC output is adjusted by R1, R2, R3, and R4 (Figure 11).

### **Sharing a Common DIN Line**

Several MAX5236/MAX5237s may share one common DIN signal line (Figure 12). In this configuration, the data bus is common to all devices; data is not shifted

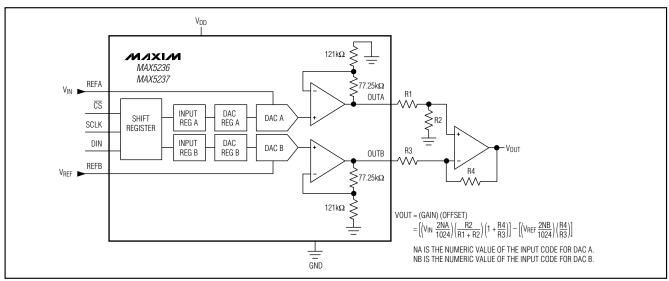


Figure 11. Digital Control of Gain and Offset

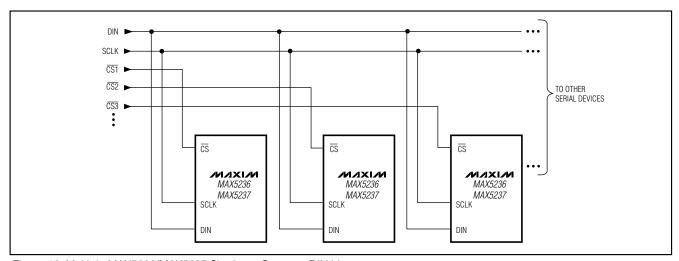


Figure 12. Multiple MAX5236/MAX5237 Sharing a Common DIN Line

through a daisy-chain. The SCLK and DIN lines are shared by all devices, but each IC needs its own dedicated  $\overline{\text{CS}}$  line.

#### **Power-Supply Considerations**

On power-up, the input and DAC registers clear (set to zero code). Bypass the power supply with a  $4.7\mu F$  capacitor in parallel with a  $0.1\mu F$  capacitor to GND. Minimize lead lengths to reduce lead inductance.

#### **Grounding and Layout Considerations**

Digital and AC transient signals on GND can create noise at the output. Connect GND to the highest quality

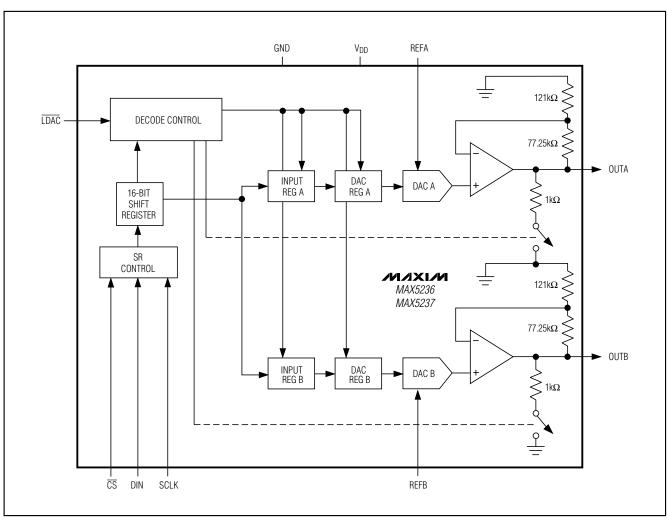
ground available. Use proper grounding techniques, such as a multilayer board with a low-inductance ground plane or star connect all ground return paths back to the MAX5236/MAX5237 GND. Carefully lay out the traces between channels to reduce AC cross-coupling and crosstalk. Wire-wrapped boards and sockets are not recommended. If noise becomes an issue, shielding may be required.

#### Chip Information

TRANSISTOR COUNT: 4184

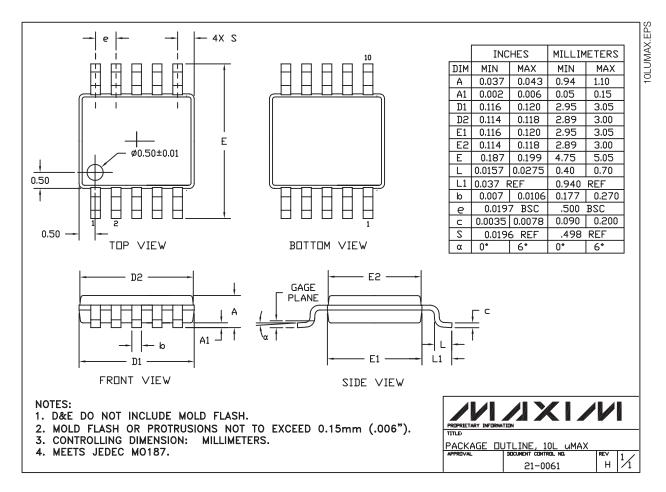
PROCESS: BICMOS

### **Functional Diagram**



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### **Package Information**



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.